FEATURES AND SPECIFICATIONS



0.6mm (.0236") Pitch FCRAM *Socket

<mark>87901</mark> Vertical, SMT



Molex introduces FCRAM* memory socket for high performance networking systems.

FCRAM* (Fast Cycle Random Access Memory) is a new technology that evolved from DRAM core architecture, creating memory products with SRAM-like performance with DRAM technology. FCRAM improves performance by using a proprietary pipeline operation and hidden pre-charge to reduce the random access cycle time to less than half of today's fastest SDRAM, Rambus and DDR memory technologies. In addition, FCRAM's highly segmented memory core uses less than half the power of SDRAM within the same effective bus bandwidth.

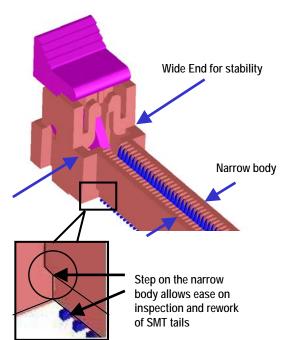
Molex's FCRAM socket allows savings on PCB real estate due to its small size pitch. It's narrow body design enables ease on SMT tail's inspection and rework. The robust latches at both ends with grippers offers safe locking of memory modules to the connector socket, and reduces micro-motion at the same time.

Molex is an active member of JEDEC work group which defines standards for the memory industry. Like Molex's other memory socket connector, the FCRAM Socket conforms to JEDEC memory socket specifications, comes in Lead Free plating and is RoHS compliant.

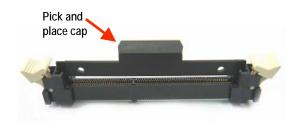
* FCRAM is a trademark of Fujitsu Ltd.

Features and Benefits

- Small footprint reduces utilization of PCB real estate
- Small form factor allows to fit in slim enclosure
- Surface mount technology enables easy processing and utilization of both sides of PCB
- Solder pads at both ends of housing provide additional mechanical strength after soldering
- Robust dual latches provide excellent module retention and easy ejection of module
- Polarization key ensures correct module orientation
- Pick-and-place cap allows automatic PCBA mounting and processing
- Wide end body design provides stability during SMT process
- Narrow body with step allows ease of inspection and rework on SMT tails
- Grippers feature reduces micro-motion and provide a secure mating







SPECIFICATIONS



0.6mm (.0236") Pitch FCRAM *Socket

Reference Information

Packaging: Tray UL File No.: E29179 CSA File No.: LR19980

Designed In: mm

Electrical Voltage:30V RMS at 60 Hz

Current: 1.0A at 30°C temperature rise Contact Resistance: 30 milliohms max. Dielectric Withstanding Voltage: 500V AC

Insulation Resistance: 1000 Megohms min.

Mechanical

Mating Force: 155.7N max. Unmating Force: 35N min.

Latch Actuation Force: 45N max. per latch

Durability: 25 Cycles

87901

Vertical, SMT

Physical

Housing: Black high-temperature LCP, UL 94V-0

Contact: Copper (Cu) Alloy

Plating:

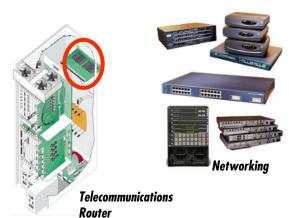
Contact Area — 0.76µm (30µ") Gold Solder Tail Area — Tin (Sn), Lead-free

Underplating — Nickel

Operating Temperature: -10°C to +85°C

APPLICATIONS

- **■**Telecommunication
 - -Switches and Routers
 - -Networking
- ■Servers and HDD
 - -1U and 2U servers
 - -Blade Servers
 - -High-end computers



Ordering Information

Description	Lead-Free Order No.	Features	
		Plating	Latch Color
0.60mm (.024") Pitch FCRAM (Fast Cycle RAM) Socket, Vertical, Single Key, Surface Mount, 160 Circuits, with Plastic Pegs and pick-and-place cap	87901-1006	0.76µm (30µ") Gold (Au) Plating	Off-White



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